

SID

Factory: Rot am See

Article:

619

ML4

Provided:

Customer:

Date:



Processtechnology: B: Pinlamination

| Material Text | Mat. Nr. | µm | Stackup | Process overview |
|---------------|----------|----|---------|------------------|
|---------------|----------|----|---------|------------------|

A-RS Kupferfolie-009my 330x490mm

9

VS

1

A-RS-FR4-Prepreg-1080-TG150-HF

60

2

C-RS-FR4-DS-1.40mm-035+035-TG150-HF

35

L2

3

1330

35

L3

A00

B00

A-RS-FR4-Prepreg-1080-TG150-HF

60

4

A-RS Kupferfolie-009my 330x490mm

9

RS

5

Thickness after Pressing

B00:

1490 µm

Tol+:

160 µm

Tol-:

160 µm

Dmax:

1650 µm

Dmin:

1330 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1600 µm

Tol+:

160 µm

Tol-:

160 µm

Dmax:

1760 µm

Dmin:

1440 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

1538 µm

Version 1.2.16.24

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